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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	72 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6.25V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c57-lpi-so

TABLE 3-1: PINOUT DESCRIPTION - PIC16C54, PIC16CR54, PIC16C56, PIC16CR56, PIC16C58, PIC16CR58

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	SOIC	SSOP			
RA0	17	17	19	I/O	TTL	Bi-directional I/O port
RA1	18	18	20	I/O	TTL	
RA2	1	1	1	I/O	TTL	
RA3	2	2	2	I/O	TTL	
RB0	6	6	7	I/O	TTL	Bi-directional I/O port
RB1	7	7	8	I/O	TTL	
RB2	8	8	9	I/O	TTL	
RB3	9	9	10	I/O	TTL	
RB4	10	10	11	I/O	TTL	
RB5	11	11	12	I/O	TTL	
RB6	12	12	13	I/O	TTL	
RB7	13	13	14	I/O	TTL	
T0CKI	3	3	3	I	ST	Clock input to Timer0. Must be tied to Vss or VDD, if not in use, to reduce current consumption.
MCLR/VPP	4	4	4	I	ST	Master clear (RESET) input/programming voltage input. This pin is an active low RESET to the device. Voltage on the MCLR/VPP pin must not exceed VDD to avoid unintended entering of Programming mode.
OSC1/CLKIN	16	16	18	I	ST	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	17	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
VDD	14	14	15,16	P	—	Positive supply for logic and I/O pins.
Vss	5	5	5,6	P	—	Ground reference for logic and I/O pins.

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input

7.6 I/O Programming Considerations

7.6.1 BI-DIRECTIONAL I/O PORTS

Some instructions operate internally as read followed by write operations. The BCF and BSF instructions, for example, read the entire port into the CPU, execute the bit operation and re-write the result. Caution must be used when these instructions are applied to a port where one or more pins are used as input/outputs. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU, bit5 to be set and the PORTB value to be written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (say bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if bit0 is switched into Output mode later on, the content of the data latch may now be unknown.

Example 7-1 shows the effect of two sequential read-modify-write instructions (e.g., BCF, BSF, etc.) on an I/O port.

A pin actively outputting a high or a low should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

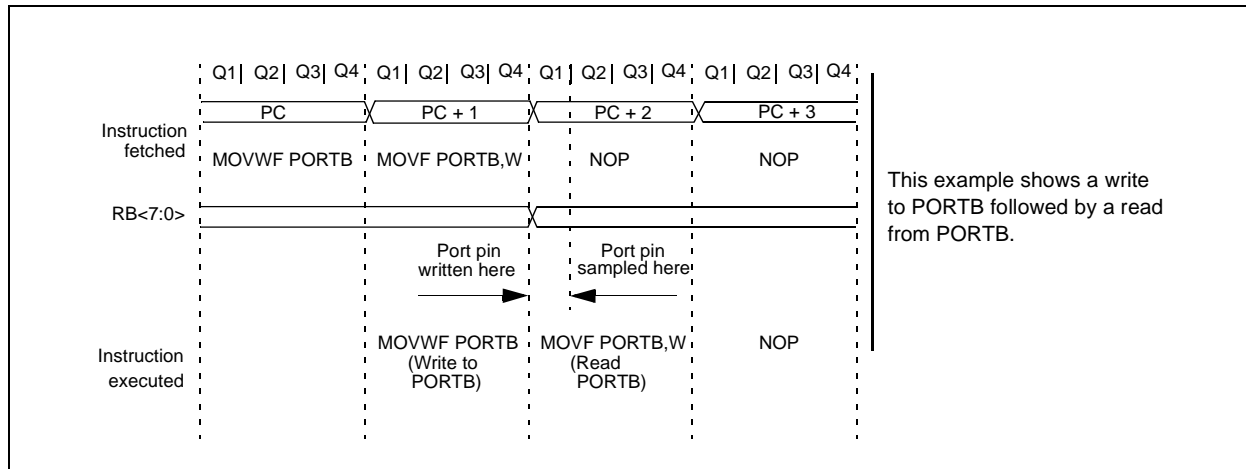
EXAMPLE 7-1: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
;Initial PORT Settings
; PORTB<7:4> Inputs
; PORTB<3:0> Outputs
;PORTB<7:6> have external pull-ups and are
;not connected to other circuitry
;
;
;          PORT latch  PORT pins
;          -----
BCF  PORTB, 7  ;01pp pppp  11pp pppp
BCF  PORTB, 6  ;10pp pppp  11pp pppp
MOVLW H'3F'    ;
TRIS  PORTB    ;10pp pppp  10pp pppp
;
;Note that the user may have expected the pin
;values to be 00pp pppp. The 2nd BCF caused
;RB7 to be latched as the pin value (High).
```

7.6.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 7-2). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction, which causes that file to be read into the CPU, is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

FIGURE 7-2: SUCCESSIVE I/O OPERATION



8.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

8.1.1 EXTERNAL CLOCK SYNCHRONIZATION

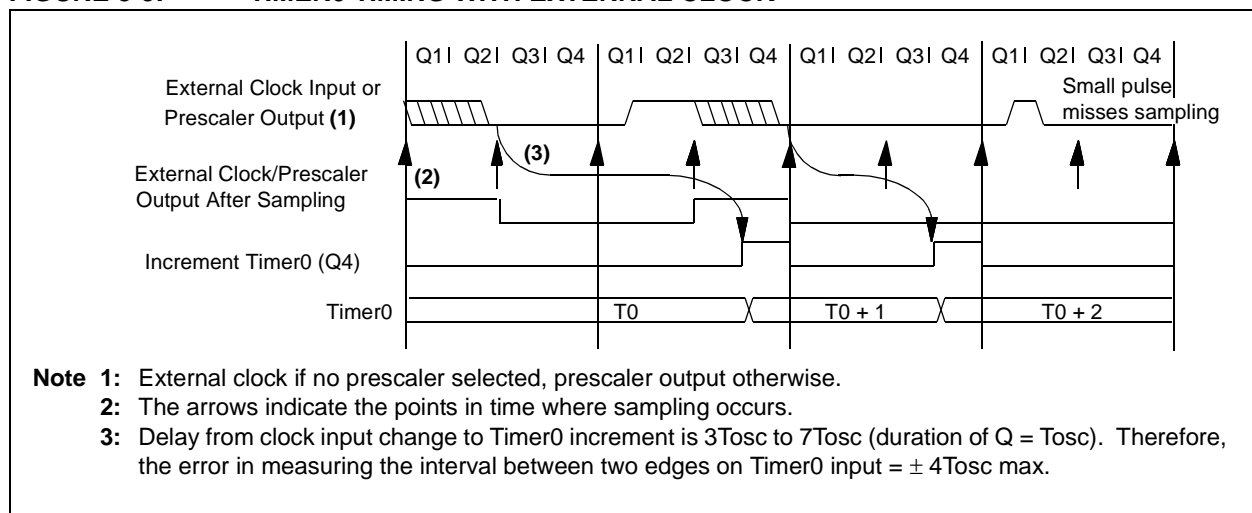
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 8-5). Therefore, it is necessary for T0CKI to be high for at least $2T_{osc}$ (and a small RC delay of 20 ns) and low for at least $2T_{osc}$ (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least $4T_{osc}$ (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

8.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 8-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 8-5: TIMER0 TIMING WITH EXTERNAL CLOCK



PIC16C5X

TABLE 10-2: INSTRUCTION SET SUMMARY

Mnemonic, Operands		Description	Cycles	12-Bit Opcode			Status Affected	Notes
				MSb	LSb			
ADDWF	f, d	Add W and f	1	0001	11df	ffff	C, DC, Z	1, 2, 4
ANDWF	f, d	AND W with f	1	0001	01df	ffff	Z	2, 4
CLRF	f	Clear f	1	0000	011f	ffff	Z	4
CLRW	—	Clear W	1	0000	0100	0000	Z	
COMF	f, d	Complement f	1	0010	01df	ffff	Z	
DECF	f, d	Decrement f	1	0000	11df	ffff	Z	2, 4
DECFSZ	f, d	Decrement f, Skip if 0	1 (2)	0010	11df	ffff	None	2, 4
INCF	f, d	Increment f	1	0010	10df	ffff	Z	2, 4
INCFSZ	f, d	Increment f, Skip if 0	1 (2)	0011	11df	ffff	None	2, 4
IORWF	f, d	Inclusive OR W with f	1	0001	00df	ffff	Z	2, 4
MOVF	f, d	Move f	1	0010	00df	ffff	Z	2, 4
MOVWF	f	Move W to f	1	0000	001f	ffff	None	1, 4
NOP	—	No Operation	1	0000	0000	0000	None	
RLF	f, d	Rotate left f through Carry	1	0011	01df	ffff	C	2, 4
RRF	f, d	Rotate right f through Carry	1	0011	00df	ffff	C	2, 4
SUBWF	f, d	Subtract W from f	1	0000	10df	ffff	C, DC, Z	1, 2, 4
SWAPF	f, d	Swap f	1	0011	10df	ffff	None	2, 4
XORWF	f, d	Exclusive OR W with f	1	0001	10df	ffff	Z	2, 4
BIT-ORIENTED FILE REGISTER OPERATIONS								
BCF	f, b	Bit Clear f	1	0100	bbbf	ffff	None	2, 4
BSF	f, b	Bit Set f	1	0101	bbbf	ffff	None	2, 4
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	0110	bbbf	ffff	None	
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	0111	bbbf	ffff	None	
LITERAL AND CONTROL OPERATIONS								
ANDLW	k	AND literal with W	1	1110	kkkk	kkkk	Z	1
CALL	k	Call subroutine	2	1001	kkkk	kkkk	None	
CLRWDT	k	Clear Watchdog Timer	1	0000	0000	0100	TO, PD	
GOTO	k	Unconditional branch	2	101k	kkkk	kkkk	None	
IORLW	k	Inclusive OR Literal with W	1	1101	kkkk	kkkk	Z	
MOVLW	k	Move Literal to W	1	1100	kkkk	kkkk	None	
OPTION	k	Load OPTION register	1	0000	0000	0010	None	
RETLW	k	Return, place Literal in W	2	1000	kkkk	kkkk	None	
SLEEP	—	Go into standby mode	1	0000	0000	0011	TO, PD	
TRIS	f	Load TRIS register	1	0000	0000	0fff	None	3
XORLW	k	Exclusive OR Literal to W	1	1111	kkkk	kkkk	Z	

Note 1: The 9th bit of the program counter will be forced to a '0' by any instruction that writes to the PC except for GOTO (see Section 6.5 for more on program counter).

- When an I/O register is modified as a function of itself (e.g. `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.
- The instruction `TRIS f`, where $f = 5, 6$ or 7 causes the contents of the W register to be written to the tristate latches of PORTA, B or C respectively. A '1' forces the pin to a hi-impedance state and disables the output buffers.
- If this instruction is executed on the TMR0 register (and, where applicable, $d = 1$), the prescaler will be cleared (if assigned to TMR0).

PIC16C5X

COMF Complement f

Syntax: [*label*] COMF f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: $(f) \rightarrow (dest)$

Status Affected: Z

Encoding:

0010	01df	ffff
------	------	------

Description: The contents of register 'f' are complemented. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example: COMF REG1, 0

Before Instruction

REG1 = 0x13

After Instruction

REG1 = 0x13

W = 0xEC

DECFSZ Decrement f

Syntax: [*label*] DECFSZ f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: $(f) - 1 \rightarrow (dest)$

Status Affected: Z

Encoding:

0000	11df	ffff
------	------	------

Description: Decrement register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example: DECFSZ CNT, 1

Before Instruction

CNT = 0x01

Z = 0

After Instruction

CNT = 0x00

Z = 1

DECFSZ Decrement f, Skip if 0

Syntax: [*label*] DECFSZ f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: $(f) - 1 \rightarrow d$; skip if result = 0

Status Affected: None

Encoding:

0010	11df	ffff
------	------	------

Description: The contents of register 'f' are decremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
 If the result is 0, the next instruction, which is already fetched, is discarded and a NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example:

HERE	DECFSZ	CNT, 1
	GOTO	LOOP
CONTINUE	•	
	•	
	•	

Before Instruction

PC = address (HERE)

After Instruction

CNT = CNT - 1;

if CNT = 0,

PC = address (CONTINUE);

if CNT \neq 0,

PC = address (HERE+1)

PIC16C5X

IORLW Inclusive OR literal with W

Syntax: [*label*] IORLW *k*
Operands: $0 \leq k \leq 255$
Operation: (W) .OR. (*k*) \rightarrow (W)
Status Affected: Z
Encoding:

1101	kkkk	kkkk
------	------	------

Description: The contents of the W register are OR'ed with the eight bit literal 'k'. The result is placed in the W register.
Words: 1
Cycles: 1
Example: IORLW 0x35

Before Instruction
W = 0x9A
After Instruction
W = 0xBF
Z = 0

IORWF Inclusive OR W with f

Syntax: [*label*] IORWF *f*,*d*
Operands: $0 \leq f \leq 31$
 $d \in [0,1]$
Operation: (W).OR. (*f*) \rightarrow (*dest*)
Status Affected: Z
Encoding:

0001	00df	ffff
------	------	------

Description: Inclusive OR the W register with register 'f'. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
Words: 1
Cycles: 1
Example: IORWF RESULT, 0

Before Instruction
RESULT = 0x13
W = 0x91
After Instruction
RESULT = 0x13
W = 0x93
Z = 0

MOVF Move f

Syntax: [*label*] MOVF *f*,*d*
Operands: $0 \leq f \leq 31$
 $d \in [0,1]$
Operation: (*f*) \rightarrow (*dest*)
Status Affected: Z
Encoding:

0010	00df	ffff
------	------	------

Description: The contents of register 'f' is moved to destination 'd'. If 'd' is 0, destination is the W register. If 'd' is 1, the destination is file register 'f'. 'd' is 1 is useful to test a file register since status flag Z is affected.
Words: 1
Cycles: 1
Example: MOVF FSR, 0

After Instruction
W = value in FSR register

MOVLW Move Literal to W

Syntax: [*label*] MOVLW *k*
Operands: $0 \leq k \leq 255$
Operation: *k* \rightarrow (W)
Status Affected: None
Encoding:

1100	kkkk	kkkk
------	------	------

Description: The eight bit literal 'k' is loaded into the W register.
Words: 1
Cycles: 1
Example: MOVLW 0x5A

After Instruction
W = 0x5A

11.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK object linker combines relocatable objects created by the MPASM assembler and the MPLAB C17 and MPLAB C18 C compilers. It can also link relocatable objects from pre-compiled libraries, using directives from a linker script.

The MPLIB object librarian is a librarian for pre-compiled code to be used with the MPLINK object linker. When a routine from a library is called from another source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications. The MPLIB object librarian manages the creation and modification of library files.

The MPLINK object linker features include:

- Integration with MPASM assembler and MPLAB C17 and MPLAB C18 C compilers.
- Allows all memory areas to be defined as sections to provide link-time flexibility.

The MPLIB object librarian features include:

- Easier linking because single libraries can be included instead of many smaller files.
- Helps keep code maintainable by grouping related modules together.
- Allows libraries to be created and modules to be added, listed, replaced, deleted or extracted.

11.5 MPLAB SIM Software Simulator

The MPLAB SIM software simulator allows code development in a PC-hosted environment by simulating the PIC series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user-defined key press, to any of the pins. The execution can be performed in single step, execute until break, or trace mode.

The MPLAB SIM simulator fully supports symbolic debugging using the MPLAB C17 and the MPLAB C18 C compilers and the MPASM assembler. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent multi-project software development tool.

11.6 MPLAB ICE High Performance Universal In-Circuit Emulator with MPLAB IDE

The MPLAB ICE universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PIC microcontrollers (MCUs). Software control of the MPLAB ICE in-circuit emulator is provided by the MPLAB Integrated Development Environment (IDE), which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB ICE in-circuit emulator allows expansion to support new PIC microcontrollers.

The MPLAB ICE in-circuit emulator system has been designed as a real-time emulation system, with advanced features that are generally found on more expensive development tools. The PC platform and Microsoft® Windows environment were chosen to best make these features available to you, the end user.

11.7 ICEPIC In-Circuit Emulator

The ICEPIC low cost, in-circuit emulator is a solution for the Microchip Technology PIC16C5X, PIC16C6X, PIC16C7X and PIC16CXXX families of 8-bit One-Time-Programmable (OTP) microcontrollers. The modular system can support different subsets of PIC16C5X or PIC16CXXX products through the use of interchangeable personality modules, or daughter boards. The emulator is capable of emulating without target application circuitry being present.

12.4 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial) PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D030	V _{IL}	Input Low Voltage					
		I/O ports	V _{SS}	—	0.2 V _{DD}	V	Pin at hi-impedance
		MCLR (Schmitt Trigger)	V _{SS}	—	0.15 V _{DD}	V	
		T0CKI (Schmitt Trigger)	V _{SS}	—	0.15 V _{DD}	V	
		OSC1 (Schmitt Trigger)	V _{SS}	—	0.15 V _{DD}	V	PIC16C5X-RC only ⁽³⁾
		OSC1 (Schmitt Trigger)	V _{SS}	—	0.3 V _{DD}	V	PIC16C5X-XT, 10, HS, LP
D040	V _{IH}	Input High Voltage					
		I/O ports	0.45 V _{DD}	—	V _{DD}	V	For all V _{DD} ⁽⁴⁾
		I/O ports	2.0	—	V _{DD}	V	4.0V < V _{DD} ≤ 5.5V ⁽⁴⁾
		I/O ports	0.36 V _{DD}	—	V _{DD}	V	V _{DD} > 5.5V
		MCLR (Schmitt Trigger)	0.85 V _{DD}	—	V _{DD}	V	
		T0CKI (Schmitt Trigger)	0.85 V _{DD}	—	V _{DD}	V	
		OSC1 (Schmitt Trigger)	0.85 V _{DD}	—	V _{DD}	V	PIC16C5X-RC only ⁽³⁾
		OSC1 (Schmitt Trigger)	0.7 V _{DD}	—	V _{DD}	V	PIC16C5X-XT, 10, HS, LP
D050	V _{HYS}	Hysteresis of Schmitt Trigger inputs	0.15 V _{DD} *	—	—	V	
D060	I _{IL}	Input Leakage Current^(1,2)					
		I/O ports	–1	0.5	+1	μA	For V_{DD} ≤ 5.5V: V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
		MCLR	–5	—	—	μA	V _{PIN} = V _{SS} + 0.25V
		MCLR	—	0.5	+5	μA	V _{PIN} = V _{DD}
		T0CKI	–3	0.5	+3	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
		OSC1	–3	0.5	+3	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , PIC16C5X-XT, 10, HS, LP
D080	V _{OL}	Output Low Voltage					
		I/O ports	—	—	0.6	V	I _{OL} = 8.7 mA, V _{DD} = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	I _{OL} = 1.6 mA, V _{DD} = 4.5V, PIC16C5X-RC
D090	V _{OH}	Output High Voltage⁽²⁾					
		I/O ports	V _{DD} – 0.7	—	—	V	I _{OH} = –5.4 mA, V _{DD} = 4.5V
		OSC2/CLKOUT	V _{DD} – 0.7	—	—	V	I _{OH} = –1.0 mA, V _{DD} = 4.5V, PIC16C5X-RC

* These parameters are characterized but not tested.

† Data in the Typical (“Typ”) column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/V_{PP} pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

13.3 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D030	V _{IL}	Input Low Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	V _{SS} V _{SS} V _{SS} V _{SS} V _{SS}	— — — — —	0.2 V _{DD} 0.15 V _{DD} 0.15 V _{DD} 0.15 V _{DD} 0.15 V _{DD}	V V V V V	Pin at hi-impedance RC mode only ⁽³⁾ XT, HS and LP modes
D040	V _{IH}	Input High Voltage I/O ports I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	2.0 0.6 V _{DD} 0.85 V _{DD} 0.85 V _{DD} 0.85 V _{DD} 0.85 V _{DD}	— — — — — —	V _{DD} V _{DD} V _{DD} V _{DD} V _{DD} V _{DD}	V V V V V V	V _{DD} = 3.0V to 5.5V ⁽⁴⁾ Full V _{DD} range ⁽⁴⁾ RC mode only ⁽³⁾ XT, HS and LP modes
D050	V _{HYS}	Hysteresis of Schmitt Trigger inputs	0.15 V _{DD} *	—	—	V	
D060	I _{IL}	Input Leakage Current^(1,2) I/O ports MCLR MCLR T0CKI OSC1	-1.0 -5.0 — -3.0 -3.0	— — 0.5 0.5 0.5	+1.0 — +5.0 +3.0 +3.0	μA μA μA μA μA	For V_{DD} ≤ 5.5V: V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance V _{PIN} = V _{SS} + 0.25V V _{PIN} = V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP modes
D080	V _{OL}	Output Low Voltage I/O ports OSC2/CLKOUT	— —	— —	0.5 0.5	V V	I _{OL} = 10 mA, V _{DD} = 6.0V I _{OL} = 1.9 mA, V _{DD} = 6.0V, RC mode only
D090	V _{OH}	Output High Voltage⁽²⁾ I/O ports OSC2/CLKOUT	V _{DD} - 0.5 V _{DD} - 0.5	— —	— —	V V	I _{OH} = -4.0 mA, V _{DD} = 6.0V I _{OH} = -0.8 mA, V _{DD} = 6.0V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

PIC16C5X

FIGURE 14-11: V_{TH} (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (XT, HS, AND LP MODES) vs. V_{DD}

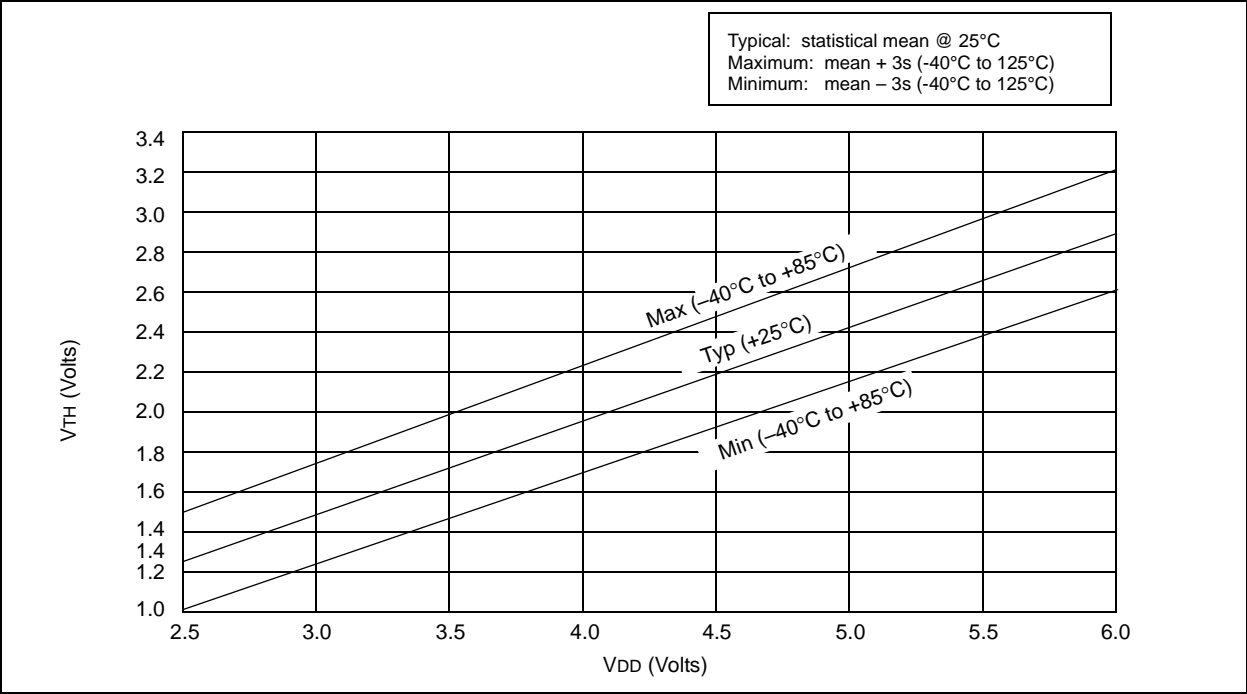


FIGURE 14-12: TYPICAL I_{DD} VS. FREQUENCY (EXTERNAL CLOCK, 25°C)

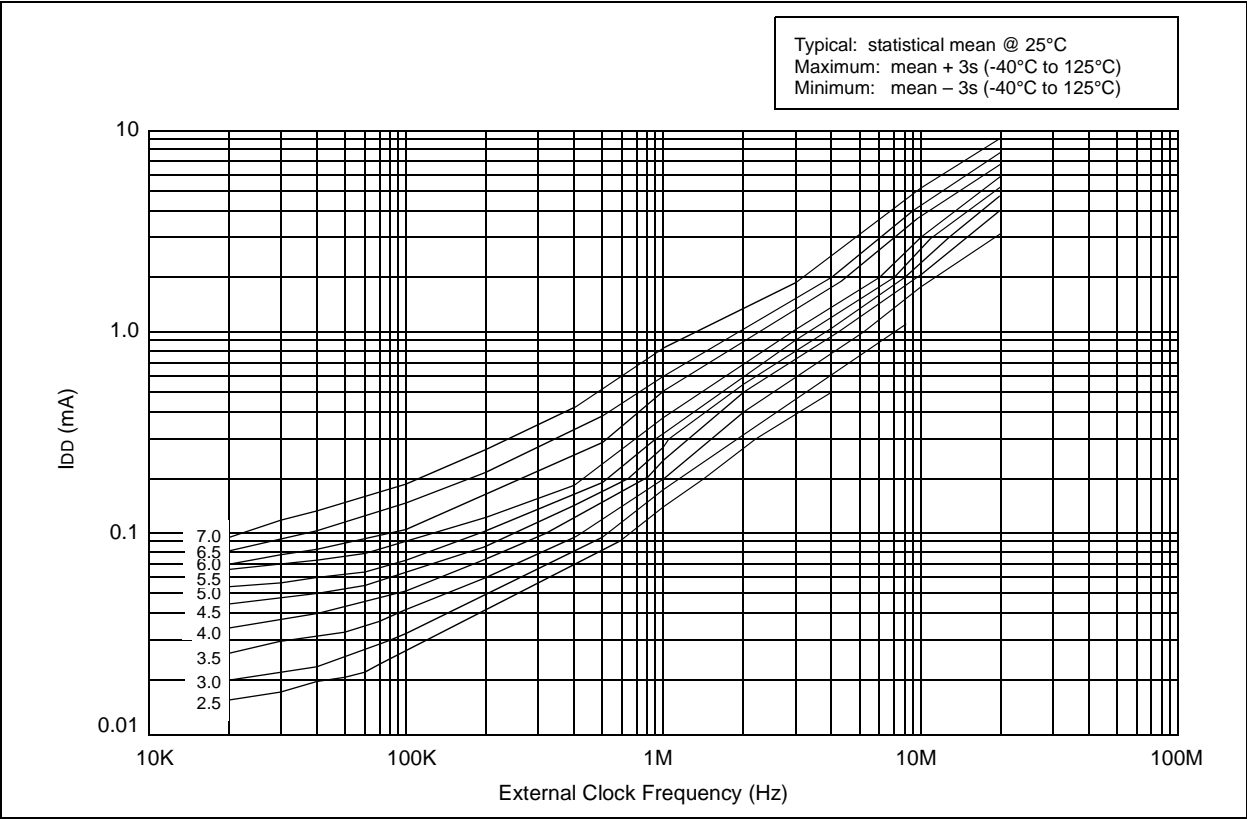


FIGURE 14-21: PORTA, B AND C IoL vs. VOL, VDD = 3 V

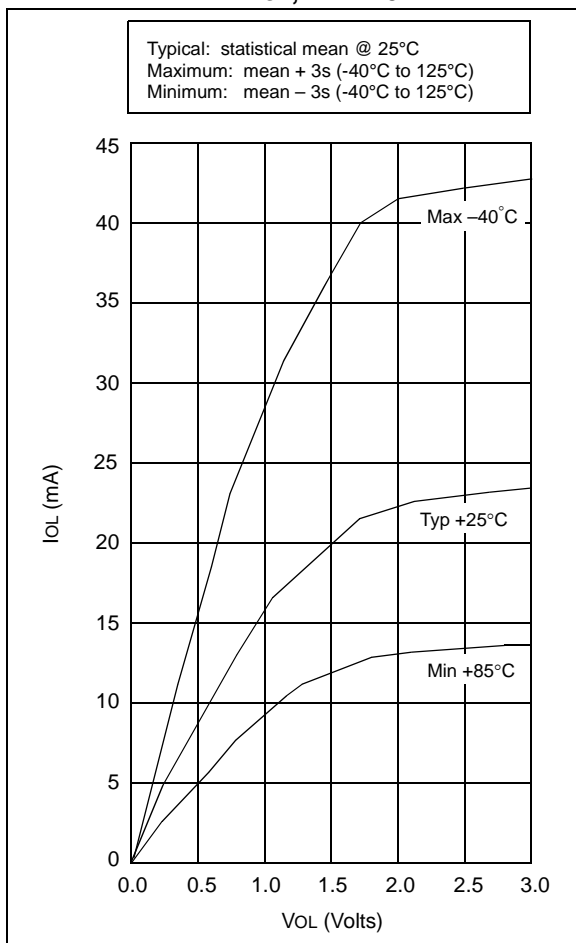
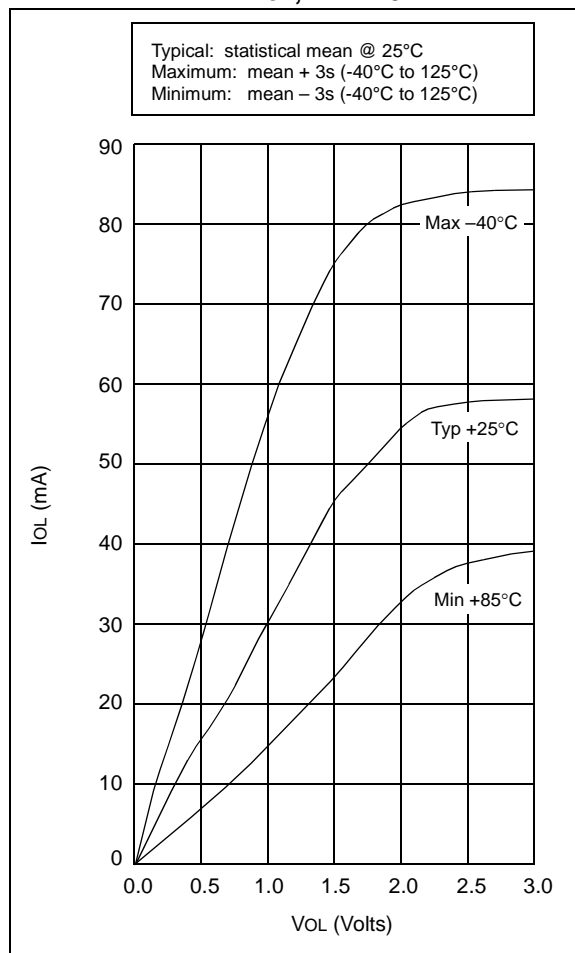


FIGURE 14-22: PORTA, B AND C IoL vs. VOL, VDD = 5 V



15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16LC54A-04E (Extended)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16C54A-04E, 10E, 20E (Extended)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D020	IPD	Power-down Current⁽²⁾					
		PIC16LC54A	—	2.5	15	μA	VDD = 2.5V, WDT enabled, Extended
			—	0.25	7.0	μA	VDD = 2.5V, WDT disabled, Extended
D020A		PIC16C54A	—	5.0	22	μA	VDD = 3.5V, WDT enabled
			—	0.8	18*	μA	VDD = 3.5V, WDT disabled

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: $I_R = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

16.0 DEVICE CHARACTERIZATION - PIC16C54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

“Typical” represents the mean of the distribution at 25°C. “Maximum” or “minimum” represents (mean + 3 σ) or (mean – 3 σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

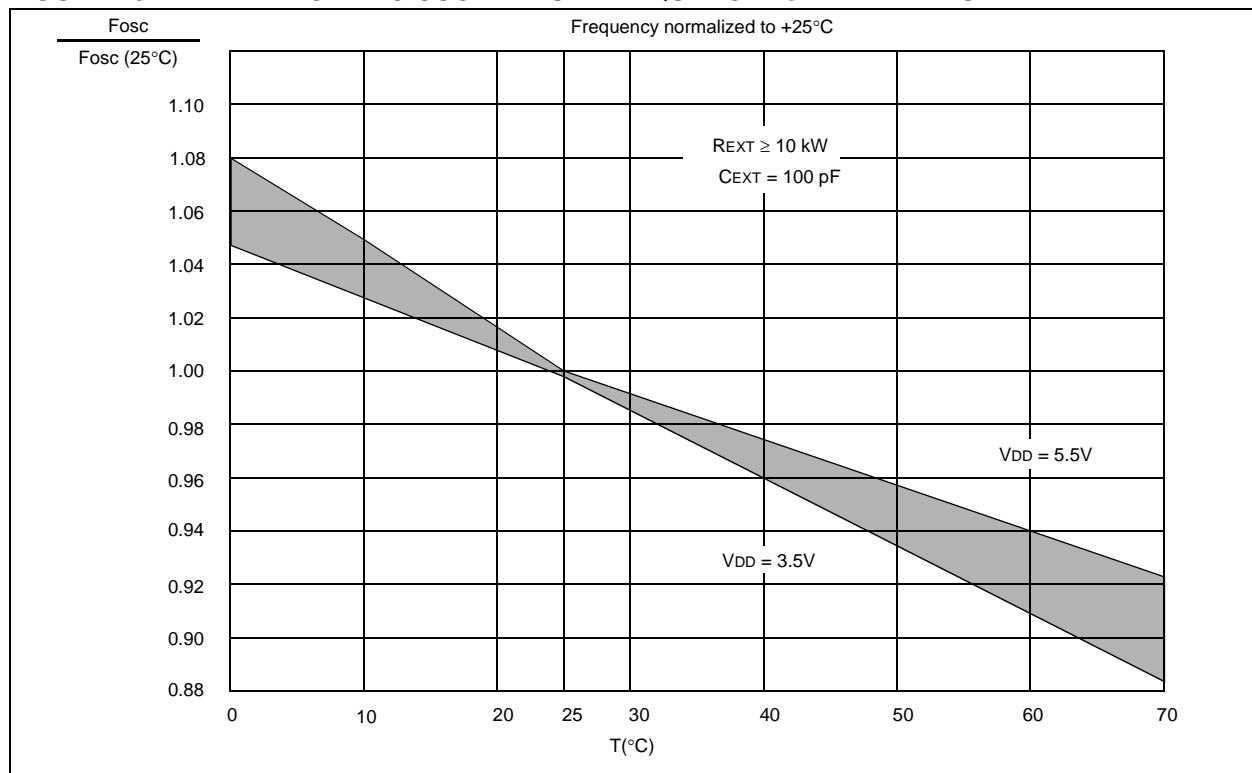


TABLE 16-1: RC OSCILLATOR FREQUENCIES

C_{EXT}	R_{EXT}	Average $F_{osc} @ 5 \text{ V}, 25^\circ\text{C}$	
20 pF	3.3K	5 MHz	$\pm 27\%$
	5K	3.8 MHz	$\pm 21\%$
	10K	2.2 MHz	$\pm 21\%$
	100K	262 kHz	$\pm 31\%$
100 pF	3.3K	1.6 MHz	$\pm 13\%$
	5K	1.2 MHz	$\pm 13\%$
	10K	684 kHz	$\pm 18\%$
	100K	71 kHz	$\pm 25\%$
300 pF	3.3K	660 kHz	$\pm 10\%$
	5.0K	484 kHz	$\pm 14\%$
	10K	267 kHz	$\pm 15\%$
	100K	29 kHz	$\pm 19\%$

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ± 3 standard deviation from average value for $V_{DD} = 5\text{V}$.

FIGURE 16-7: V_{TH} (INPUT THRESHOLD VOLTAGE) OF I/O PINS - V_{DD}

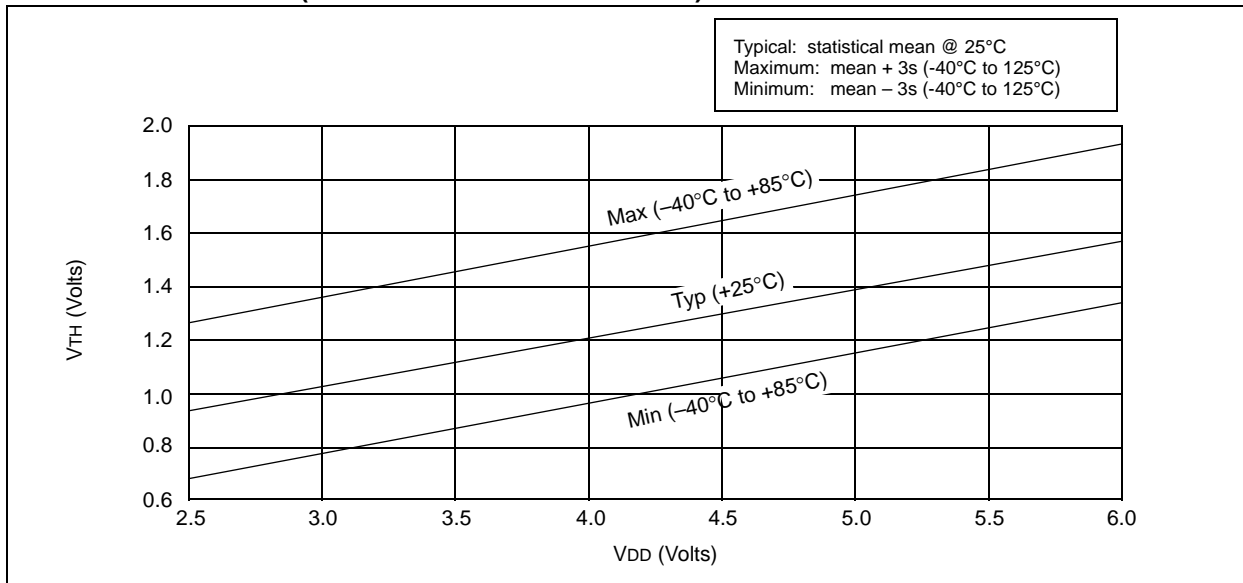


FIGURE 16-8: V_{TH} (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (IN XT, HS, AND LP MODES) vs. V_{DD}

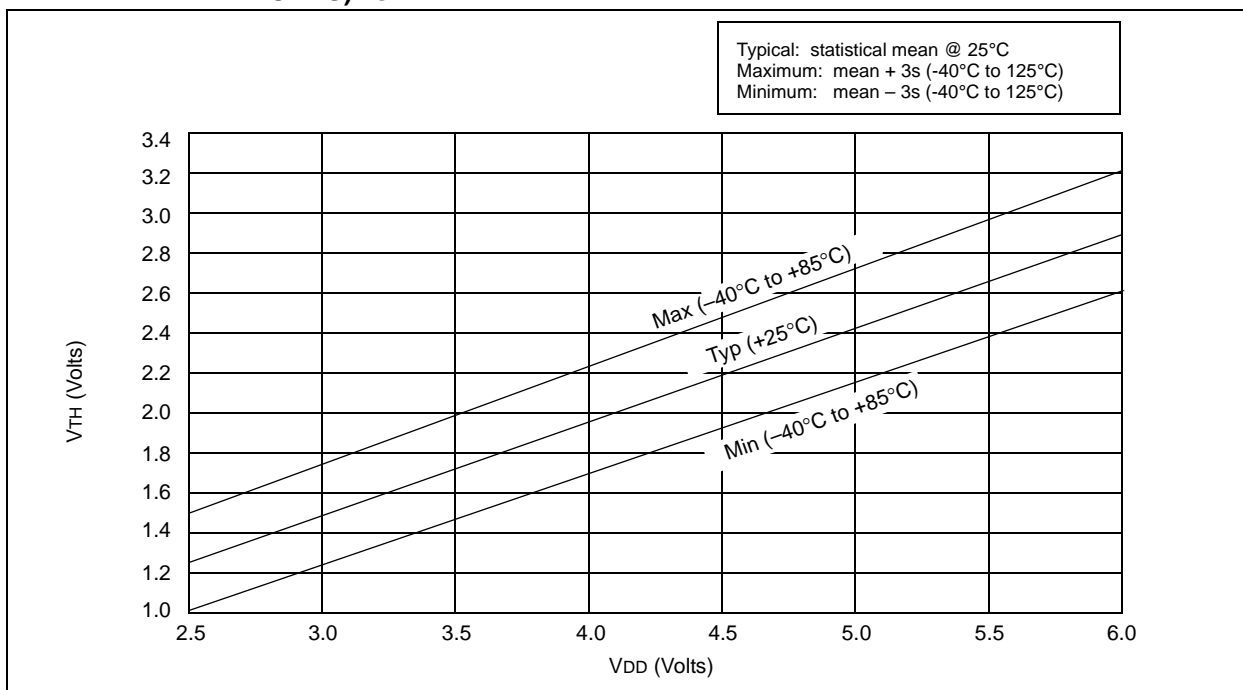


FIGURE 16-10: TYPICAL I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, 25°C)

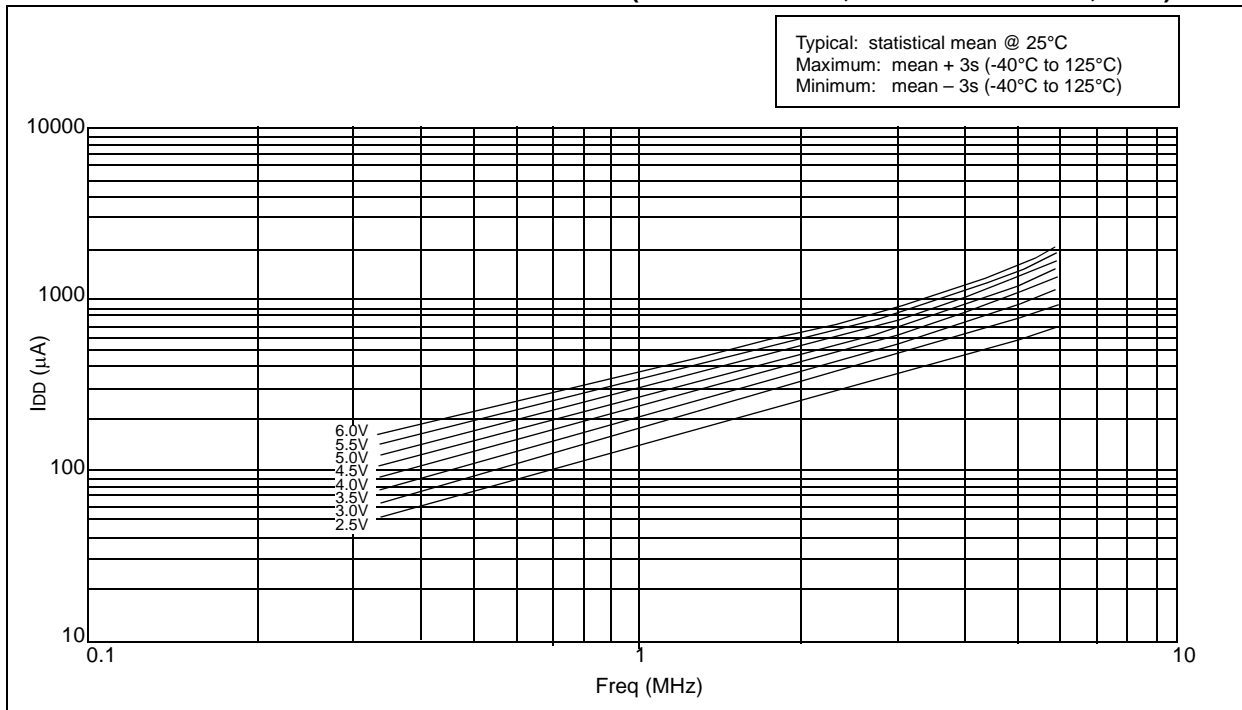


FIGURE 16-11: MAXIMUM I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, -40°C to +85°C)

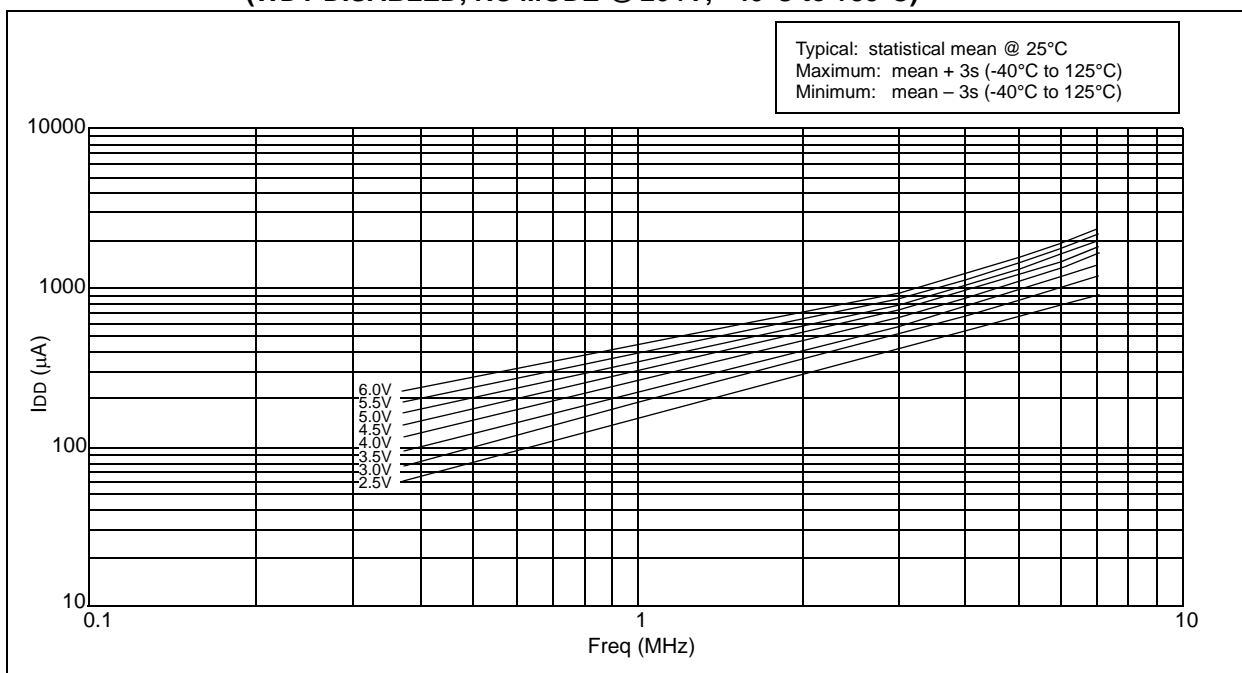


FIGURE 16-14: TYPICAL I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, 25°C)

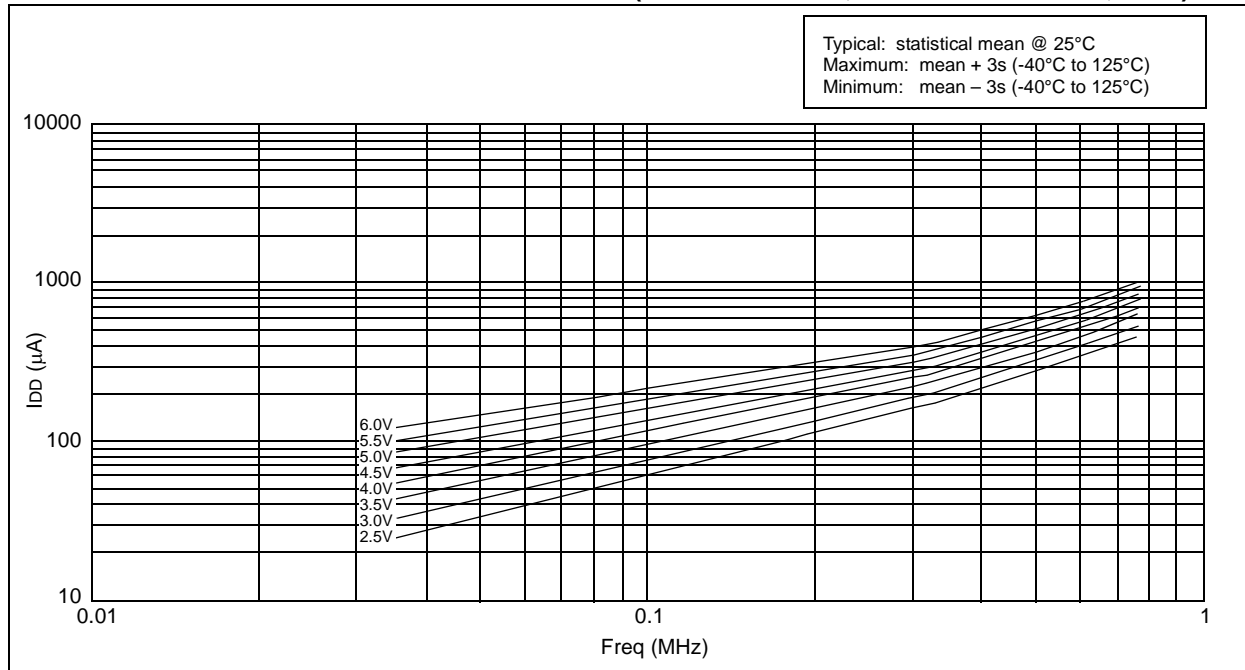


FIGURE 16-15: MAXIMUM I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, -40°C to +85°C)

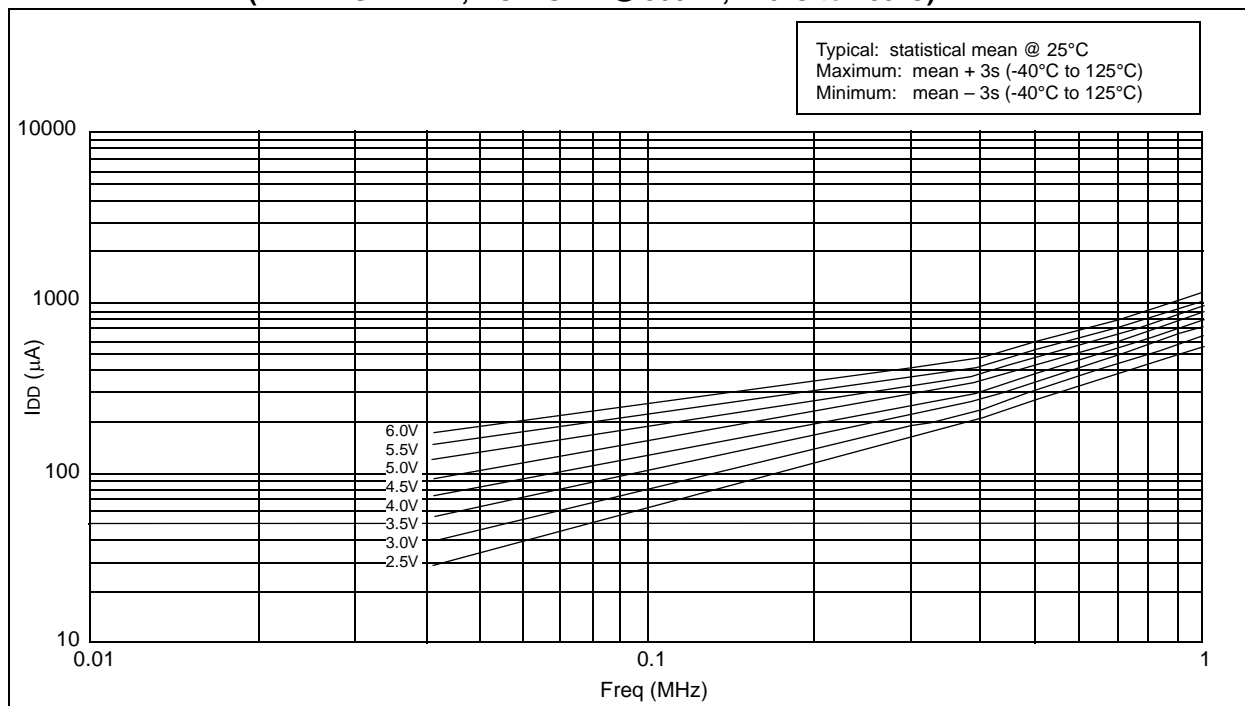


FIGURE 18-16: PORTA, B AND C I_{OH} vs. V_{OH} , $V_{DD} = 5\text{ V}$

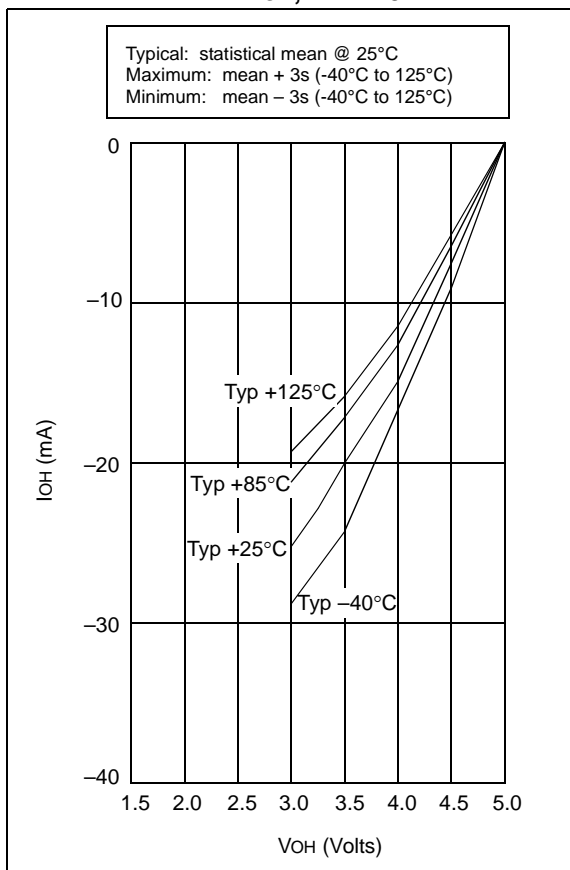


FIGURE 18-17: PORTA, B AND C I_{OL} vs. V_{OL} , $V_{DD} = 3\text{ V}$

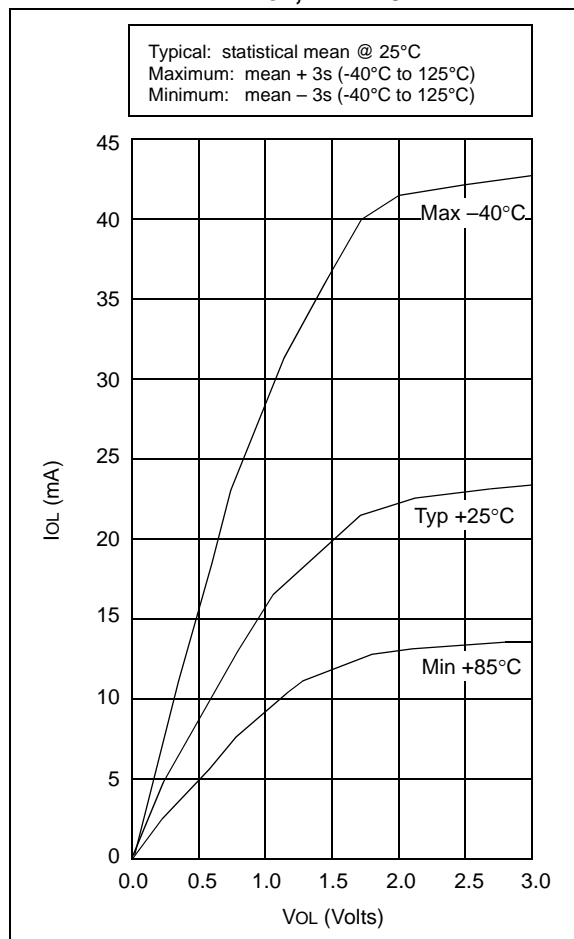
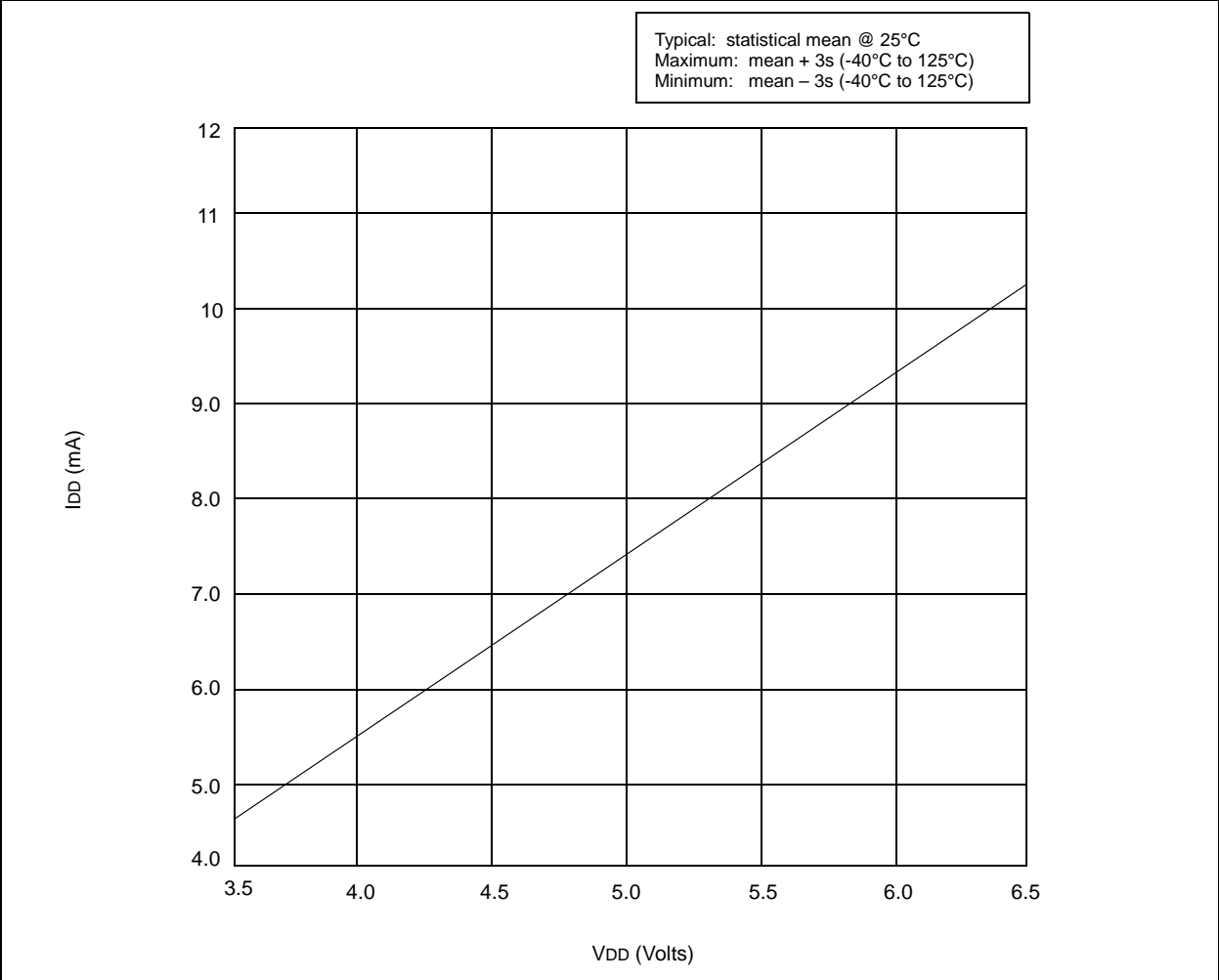


FIGURE 20-6: TYPICAL I_{DD} vs. V_{DD} (40 MHZ, WDT DISABLED, HS MODE, 70°C)



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